
WEVOSIL 22066 FL

Solvent-free, addition-curing two-component silicone-based casting resin system.

Attributes

The resulting soft-elastic molded material is characterized by good low-temperature flexibility and excellent behavior in the temperature shock test. Recommended temperature range: -60 °C to +180 °C.

The resin is processed together with WEVOSIL 22066 FL B.

Application

- Pressure-sensitive electrical components
- Complete assemblies in SMD technology
- Thermally conductive adhesive and potting as well as molded parts made of this material

Standards

- Temperature application range -60 °C - +180 °C
- Isolation class H
- RTI 180°C

Delivery forms

10 kg and 30 kg containers

Color

WEVOSIL 22066 FL A: Natural

WEVOSIL 22066 FL B: Blue

Storage

Polymer (A-component) and crosslinker (B-component) must be stored dry and at a temperature of 5 °C to 30 °C and not in the open air. The containers should be stored upright and not directly on the cold floor (floor temperature not below 5 °C). WEVOSIL 22066 FL has a shelf life of 6 months after production.

At temperatures above 25 °C, the settling of the fillers contained in the casting compound is accelerated. The potting compound is then more difficult to homogenize.

Hardening

- Pot life: 50-70 minutes at room temperature, depending on layer thickness and casting volume.
- Curing time: 6 hours at room temperature, 1 hour at 100 °C
- Final chemical curing: several days at room temperature

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Curing notes:

- Excessive humidity has a damaging effect on the uncured compound. If necessary, curing should take place in an air-conditioned room, a container with low humidity or in an oven.
- Curing at an elevated temperature (50 - 100 °C) accelerates the curing reaction and can influence the adhesion of the potting compound to the walls of the component.
- The WEVOSIL 22066 FL casting compound reaches its final hardness after a few days at room temperature.
- After approx. 6 hours curing at room temperature (or 1 h @ 100 °C) approx. 90 - 95 % of the Curing takes place. To achieve the final hardness, post-curing can then be carried out for 2 hours at 165 - 180 °C. However, this last step is not absolutely necessary. After a few days, the casting compound reaches its final hardness even at room temperature (depending on the system).
- Electrical tests of the component quality can usually be carried out after the first curing (6 hours at room temperature or 1 h @ 100 °C).

Protection

Our products are intended solely for industrial use. For further details, please refer to the safety data sheet.

Processing

Our processing instructions please find [here](#).

General	Unit of measure	Condition	Value	Test method
Mixing ratio	Gew-%		100:100	
Pot life	min	25 °C	50-70	
Curing time	h	25 °C	6	
Curing time	h	100 °C	1	

Mechanical	Unit of measure	Condition	Value	Test method
Density	g/cm ³	WEVOSIL 22066 FL A	1.56-1.60	
Density	g/cm ³	WEVOSIL 22066 FL B	1.56-1.60	
Viscosity	mPas	WEVOSIL 22066 FL A / 22 °C	1500-2500	
Viscosity	mPas	WEVOSIL 22066 FL B / 22 °C	1500-2500	
Mixture viscosity		22 °C	1500-2500	
Hardness	Shore A		35-45	ISO 48-4
Water absorption	%	30 d, RT	<0.5	
Elongation at break	%		40	ISO 527-2

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Thermal	Unit of measure	Condition	Value	Test method
Thermal class			H	DIN EN 60085
Glass transition temperature	°C		-45	TMA
Thermal conductivity	W/m*K		0.8	ISO 22007-2:2008

Electrical	Unit of measure	Condition	Value	Test method
Dielectric strength	kV/mm		>25	DIN EN 60243
Dielectric constant ε at 50 Hz, 23 °C			3.9	DIN EN 60250
Dielectric constant; at 1 kHz, 23 °C			3.9	DIN EN 60250
Dielectric constant ε at 1 MHz, 23 °C			3.9	DIN EN 60250
Volume resistance specific at 23 °C, 50 % r.h.	Ωxcm		>10 ¹⁴	DIN EN 62631-3-1:2016
Surface resistivity at 23°C and 50 % r.h.	Ω		>10 ¹⁴	DIN EN 62631-3-2:2016

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